



FACSIMILE

TO: Examiner Kimberly A. Stewart
Art Unit 1791
Via Facsimile No. 571-270-8004

FROM: Michael J. Caridi
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DATE: July 2, 2010

Re: U.S. Patent Application No. 10/584,922
Inventor: S. MATSUBAYASHI, et al.
Our Reference: 062663

No of Pages: 4 (including cover page)

Message:

Per our telephone conversation on June 30, 2010, enclosed is our proposed agenda for this July 6, 2010 interview.

We look forward to speaking with you and Examiner Del Sole.

In the meantime, if you have any questions please do not hesitate to contact us.


Michael J. Caridi

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(1) First added feature in the last amendment of February 19, 2010, that the resin reservoir pots vertically penetrate the upper die.

At section 13 on page 5 of the Office Action, the reasons presented as to why a skilled artisan would utilize a configuration wherein the reservoir pots vertically penetrate the upper die in Shiga based on Osada and Sera are: (1) for the benefit of having flexibility as to where the resin pots can be placed; (2) so resin can expand and force out unwanted air and moisture; or (3) for the benefit of being able to be pressed by a plunger and forced out through runners and gates into the cavities.

Reasons (1) and (2) are based upon Osada, these reasons do not appear to be viable reason for a skilled artisan to use a vertically penetrating reservoir pot in an upper die. Vertical penetration of the upper die does not increase flexibility of placement of the reservoir pots per reason (1). Reason (2) is taken from col. 7, lines 35-47 of Osada which relates to upward movement of a resin from a lower mold.

Reason (3) is based on the general teachings of Sera. However, the rejection does not explain why a skilled artisan would have a reason to modify the formation of the device of Shiga based on the reference. Shiga does not disclose a specific molding apparatus only Osada and Sera are relied upon for an apparatus. Specifically, there is no basis from the general teachings of Sera which would cause a skilled artisan to realize an improvement therein by modifying the upper die of Osada so as to have reservoir pots which vertically penetrate the upper die. Rather, Osada, as noted above, is concerned with pressurizing and removing air from the resin pathway

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and utilizing a reservoir pot 53 in the lower die 52 to take advantage of the pressurizing action.

Thus, Osada teaches away from such a combination.

(2) Second feature added in the last amendment of February 19, 2010, regarding the positioning of the reservoirs in relation to the permanent magnets and the use of pathways on the lower surface of the upper die.

To address the poisoning of the reservoirs the rejection cites to col. 6, lines 61-67 of Osada. This section of Osada indicates that a resin tablet is placed in a pot of an upper mold and fed through pathways to encapsulate the chips. The rejection further states that the positioning of the pathway in relation to the magnets is merely a re-arrangement of parts which would be a matter of routine experimentation to the skilled artisan. Specifically, the rejection notes that Shiga teaches multiple arrangements of magnets and maintains that a skilled artisan would arrive at the claimed method to seal the magnets based on devising a method to fill resin in one of these multiple arrangements. See sections 14 and 15 on pages 5 and 6 of the Office Action.

First, Osada is clearly directed to encapsulation of semiconductor chips and to a method which provides for encapsulation of multiple chips at one time. Thus, Osada is teaching a pathway 57 in order to reach multiple chips 62, 63 per single process. Second, Shiga does teach multiple arrangements. However, none of the arrangements noted in Figs. 11-16 provide for placing the resin inward from the rotor core. Rather these arrangements are meant to provide proper poles for the magnets within the motor. See Fig. 14. For a feature to be obvious there must be a reason for a skilled artisan to combine the references in the manner set forth in the claims. In the current invention, the claims are directed to resin flowing from an inward position

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of the reservoirs 50 along a path 51 on the lower surface of an upper die 37. This allows for proper placement of the magnets 47 in relation to the rotor core 36 with the resin not being placed between the magnet 47 and the rotor core 36. There is no reason whereby a skilled artisan would device this placement based on the combined teachings of Shiga and Osada.